

**DESCRIPTION**

The AM65N07PJ is available in PDFN8(5x6) package.

BVDSS	RDSON	ID
68V	7mΩ	64A

**Application**

- Motor Control
- Battery Management System
- Power Management
- Rectifier

**ORDERING INFORMATION**

Package Type	Part Number	
PDFN8(5x6) SPQ:4,000pcs/Reel	PJ8	AM65N07PJ8R
Note	R: Tape & Reel	
AiT provides all RoHS products		

**ABSOLUTE MAXIMUM RATINGS**

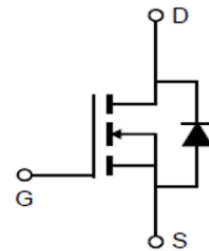
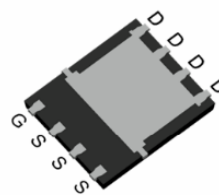
TC= 25°C, unless otherwise specified.

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	68	V
Gate-Source Voltage	$V_{GS}$	±20	V
Drain Current-Continuous	$I_D$	$T_A = 25^\circ\text{C}$	64
		$T_A = 100^\circ\text{C}$	41
Pulsed Drain Current	$I_{DM}$	256	A
Single Pulse Avalanche Energy	$E_{AS}$	272	mJ
Power Dissipation	$P_D$	$T_C = 25^\circ\text{C}$	66
		$T_A = 25^\circ\text{C}$	1.7
Operation Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 ~ 150	°C
Thermal Resistance, Junction-to-ambient <sup>1</sup>	$R_{\theta JA}$	75	°C/W
Thermal Resistance, Junction-to-case <sup>1</sup>	$R_{\theta JC}$	1.9	°C/W

Stresses above may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the Electrical Characteristics are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**FEATURES**

- 68V, 64A  
 $R_{DS(ON)}$  Typ = 7mΩ @  $V_{GS} = 10\text{V}$
- Low reverse transfer capacitances
- ΔVDS test
- 100% single pulse avalanche energy test

**PIN DESCRIPTION**

Pin#	Symbol	Function
1, 2, 3	S	Source
4	G	Gate
5,6,7,8	D	Drain

**ELECTRICAL CHARACTERISTICS**T<sub>J</sub> = 25°C, unless otherwise specified.

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	68	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V,	-	-	1.0	μA
Gate to Body Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V	-	-	±100	nA
<b>On Characteristics</b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	2.0	3.0	4.0	V
Static Drain-Source on-Resistance note3	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =30A	-	7	8	mΩ
Transconductance	G <sub>fs</sub>	V <sub>DS</sub> =5V, I <sub>D</sub> =30A	-	36	-	S
<b>Dynamic Characteristics</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =35V, V <sub>GS</sub> =0V, f=1.0MHz	-	2859	-	pF
Output Capacitance	C <sub>oss</sub>		-	193	-	pF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	160	-	pF
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =35V, I <sub>D</sub> =30A, V <sub>GS</sub> =10V	-	59	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	17	-	nC
Gate-Drain("Miller") Charge	Q <sub>gd</sub>		-	19	-	nC
Gate plateau voltage	V <sub>plateau</sub>		-	5.8	-	V
<b>Switching Characteristics</b>						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DS</sub> =35V, R <sub>G</sub> =3Ω, V <sub>GS</sub> =10V	-	13	-	ns
Turn-on Rise Time	t <sub>r</sub>		-	28	-	ns
Turn-off Delay Time	t <sub>d(off)</sub>		-	34	-	ns
Turn-off Fall Time	t <sub>f</sub>		-	11	-	ns
Gate resistance	R <sub>G</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz	-	1.4	-	Ω
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Maximum Continuous Drain to Source Diode Forward Current	I <sub>S</sub>	-	-	-	64	A
Drain to Source Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =30A	-	-	1.2	V
Body Diode Reverse Recovery Time	T <sub>rr</sub>	I <sub>F</sub> =30A, dI/dt=100A/μs	-	29	-	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>		-	21	-	nC



## TYPICAL PERFORMANCE CHARACTERISTICS

Fig 1. Maximum Continuous Drain Current vs. Drain-Source Voltage

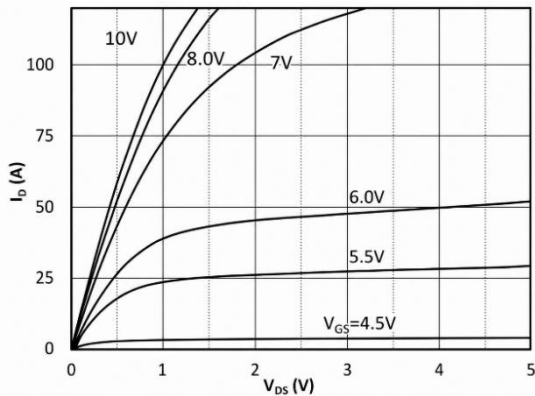


Fig 2. Maximum Continuous Drain Current vs. Gate-Source Voltage

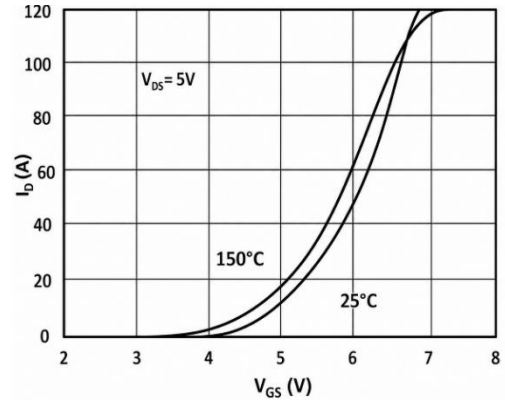


Fig 3. Static Drain-Source On-Resistance vs. Continuous Drain Current

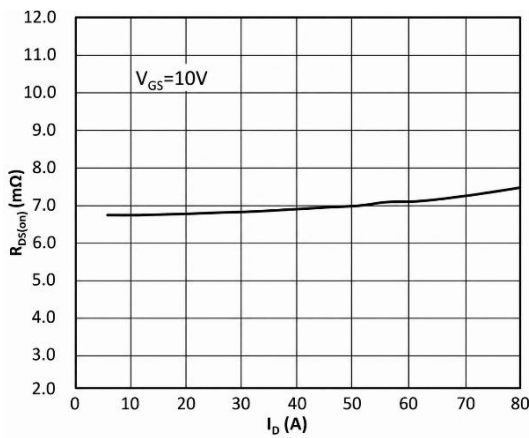


Fig 4. Static Drain-Source On-Resistance vs. Gate-Source Voltage

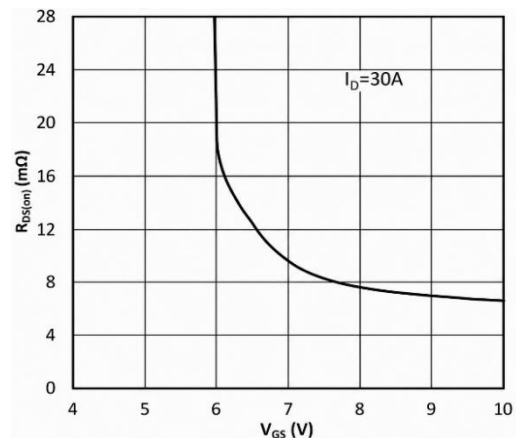


Fig 5. Static Drain-Source On-Resistance vs. Junction Temperature

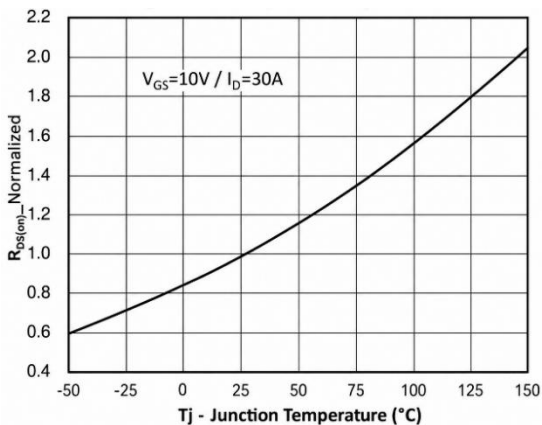


Fig 6. Capacitance vs. Drain-Source Voltage

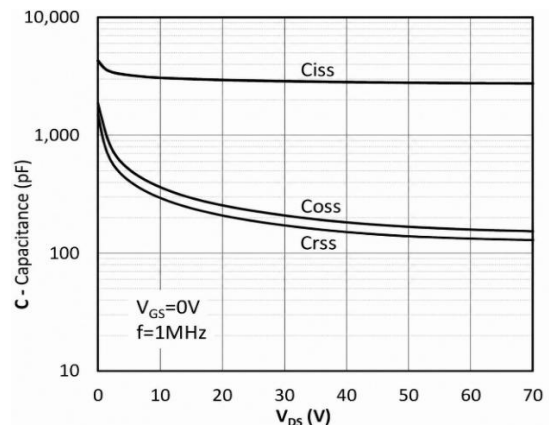
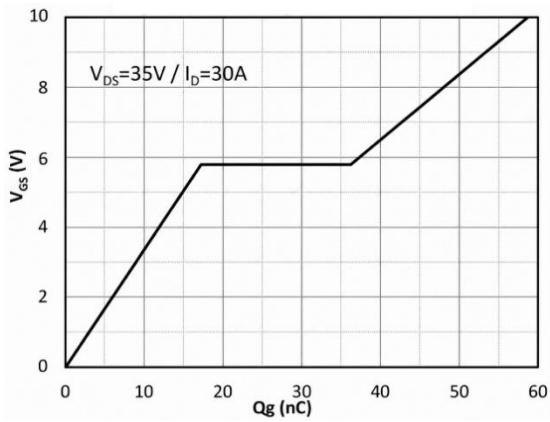


Fig 8. Diode Forward Current



Fig 7. Gate-Source Voltage vs Total Gate Charge



vs. Drain to Source Diode Forward Voltage

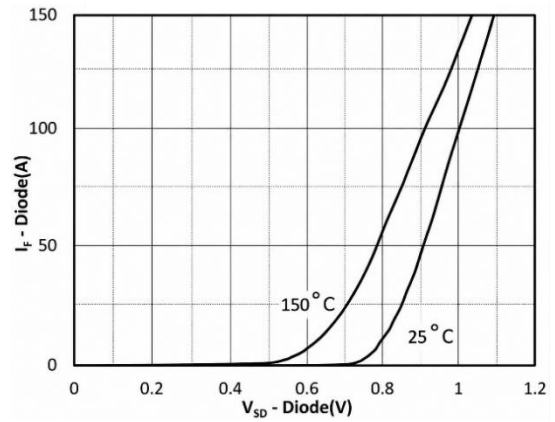


Fig 9. Total Power Dissipation vs. Case Temperature

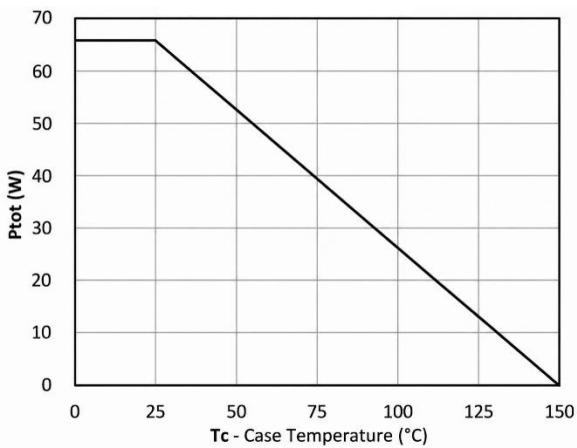


Fig 10. Maximum Continuous Drain Current vs. Case Temperature

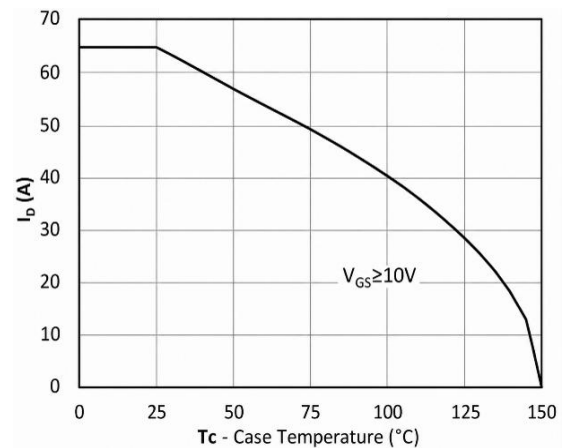


Fig 11. Maximum Continuous Drain Current vs. Drain-Source Voltage

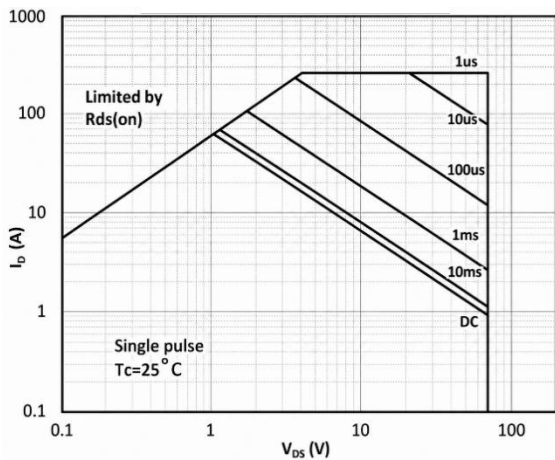
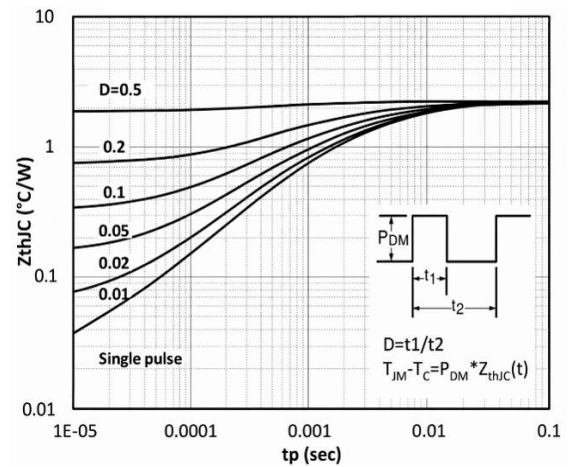


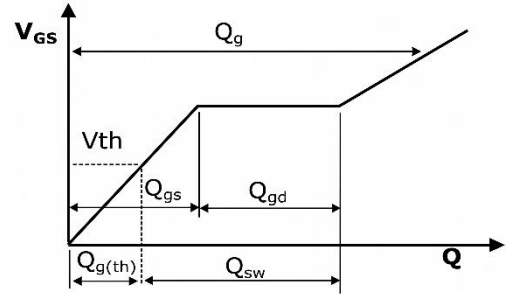
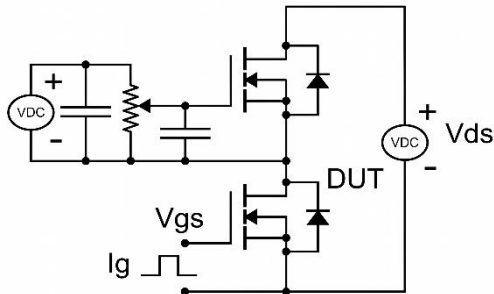
Fig 12. Transient Thermal Impedance vs. Pulse Time(sec)



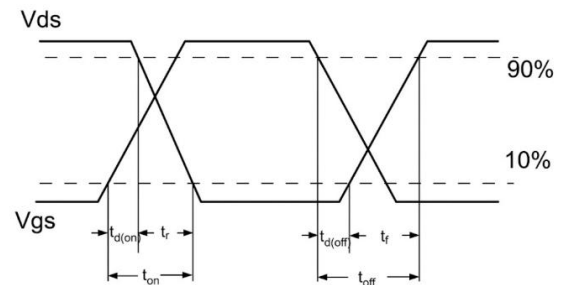
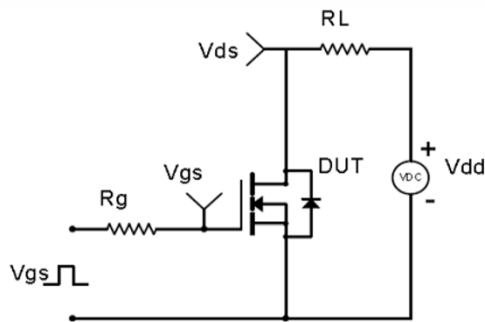


### Test Circuit & Waveform

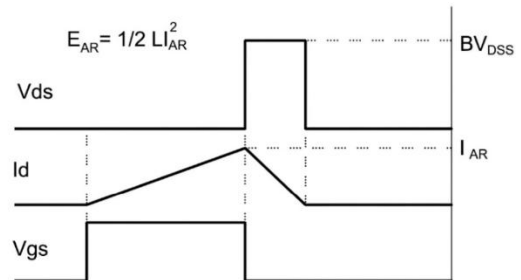
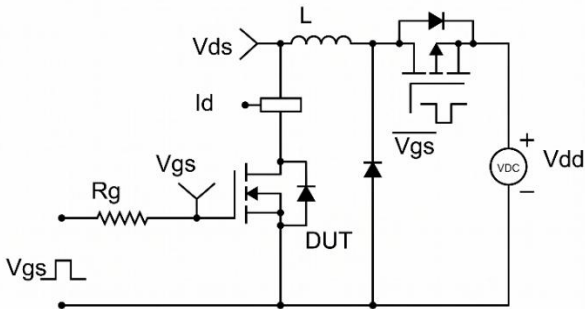
Gate Charge Test Circuit & Waveform



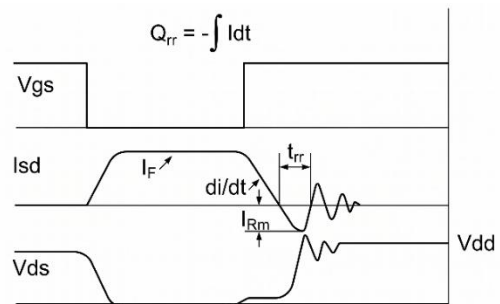
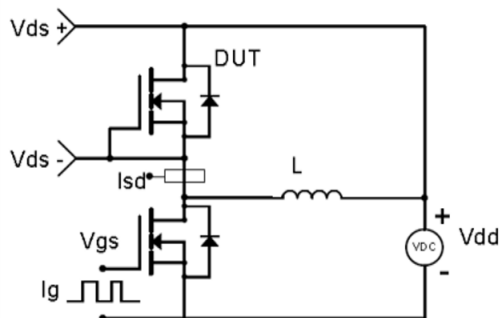
MOSFET Switching Test Circuit & Waveform



EAS Test Circuit & Waveform



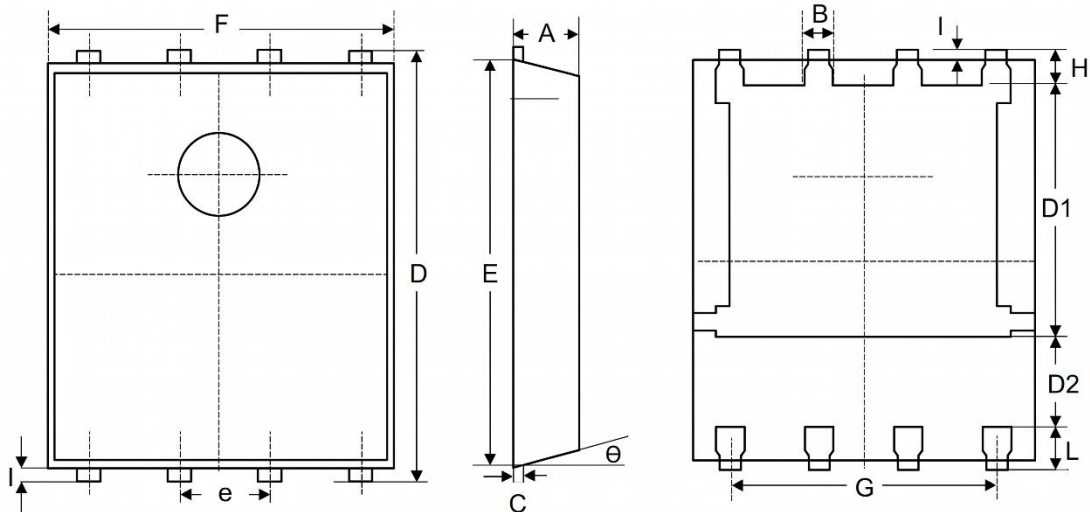
Diode Recovery Test Circuit & Waveform





**PACKAGE INFORMATION**

Dimension in PDFN8(5x6) (Unit: mm):



Symbol	Millimeters	
	Min	Max
A	0.900	1.100
B	0.330	0.510
C	0.200	0.300
D	5.900	6.100
D1	3.380	3.780
D2	1.100	-
E	5.700	5.800
e	1.270 BSC	
F	4.800	5.000
G	0.361	0.396
H	0.410	0.610
I	0.060	0.200
L	0.510	0.710
θ	0°	12°



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